

**PCN# : P183A**  
**Issue Date : Sep. 14, 2011**

## **DESIGN/PROCESS CHANGE NOTIFICATION**

This is to inform you that a change is being made to the products listed below.

Unless otherwise indicated in the details of this notification, the identified change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications. Products incorporating this change may be shipped interchangeably with existing unchanged products.

This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local Fairchild Sales Representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples. Alternatively, you may send an email request for data, samples or other information to [PCNSupport@fairchildsemi.com](mailto:PCNSupport@fairchildsemi.com).

### **Implementation of change:**

Expected First Shipment Date for Changed Product : Dec. 13, 2011

Expected First Date Code of Changed Product :1138

Last Date for Shipment of Unchanged Product : Dec. 13, 2011

Description of Change (From) :

For all of SPM45H,SPM3V, and SPM3F, use Ag Epoxy D/A for Boot strap diode

Description of Change (To) :

For all of SPM45H,SPM3V, and SPM3F,add below D/A material for Boot strap diode beside current Ag epoxy: solder Pb92.5Sn5Ag2.5.

Reason for Change:

To improve Die attach quality of Boot strap diode

**Affected Product(s):**

FSBB15CH60C	FNA41060B2	FNA40860
FSBB20CH60CL	FNA40860B2	FSBB30CH60C
FSBB20CH60CT	FNE41060	FSBF10CH60BT
FSBF10CH60BTL	FSBB20CH60C_F139	FNA41560B2
FNB41560	FSBB20CH60C	FSBF15CH60CT
FNB41060	FSBF5CH60BS	FNB40560
FNA41560B2_F057	FSBF5CH60B	FNB41060B2
FNA41060	FSBF15CH60BTH	FNB41560B2
FCBB20CH60SF	FSBF10CH60B	FSBF15CH60BT
FNA40560	FNA41560	FSBF3CH60B

Qualification Plan	Device	Package	Process	No. of Lots
F20110491A	FNA41560	SPM45H		3

Test Description:	Condition:	Standard :	Duration:	Results:
Temperature Cycle	-40C, 125C	JESD22	500 cycles	0/75
Reflow	245degree C	N/A	5 cycles	0/75
HAST	130C, 85%RH	JESD22	96hrs	0/75

Qualification Plan	Device	Package	Process	No. of Lots
F20110478A	FSBB20CH60C	SPM27-CC	Solder D/A	3

Test Description:	Condition:	Standard :	Duration:	Results:
Temperature Cycle	-40C, 125C	JESD22	200 cycles	0/75
Reflow	245degree C	N/A	5 times	0/75
HAST	130C,85%RH	JESD22	96hrs	0/75